

SN74AS1008A QUADRUPLE 2-INPUT POSITIVE-AND BUFFER/DRIVER

SDAS071B – DECEMBER 1982 – REVISED JANUARY 1995

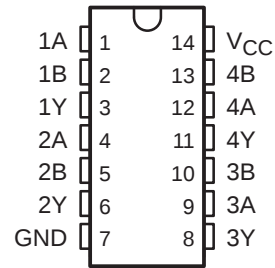
- Driver Version of 'AS08
- Offers High Capacitive-Drive Capability
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs

description

This device contains four independent 2-input positive-AND buffers/drivers. It performs the Boolean functions $Y = A \bullet B$ or $Y = \overline{A + B}$ in positive logic.

The SN74AS1008A is characterized for operation from 0°C to 70°C.

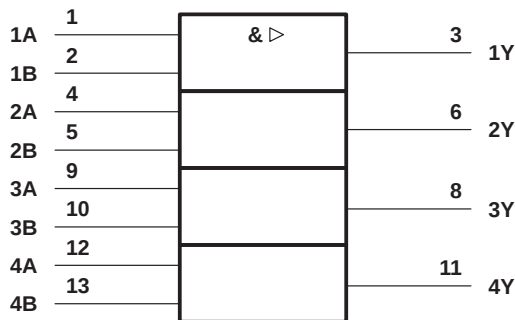
D OR N PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each gate)

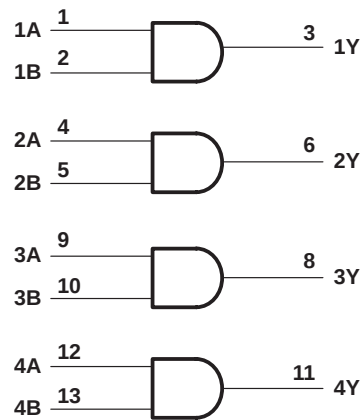
INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN74AS1008A

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recommended operating conditions[†]

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			–48	mA
I _{OL}	Low-level output current			48	mA
T _A	Operating free-air temperature	0		70	°C

[†] This high sink- or source-current device is not recommended for use above 40 MHz.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA			–1.2	V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = –2 mA	V _{CC} – 2			V
	V _{CC} = 4.5 V, I _{OH} = –3 mA	2.4	3.2		
	V _{CC} = 4.5 V, I _{OH} = –48 mA	2			
V _{OL}	V _{CC} = 4.5 V, I _{OL} = 48 mA	0.35	0.5		V
I _I	V _{CC} = 5.5 V, V _I = 7 V		0.1		mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V		20		μA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V		–0.5		mA
I _O [§]	V _{CC} = 5.5 V, V _O = 2.25 V	–50		–200	mA
I _{CCH}	V _{CC} = 5.5 V, V _I = 4.5 V		5.6	9.5	mA
I _{CCL}	V _{CC} = 5.5 V, V _I = 0		13.5	22	mA

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

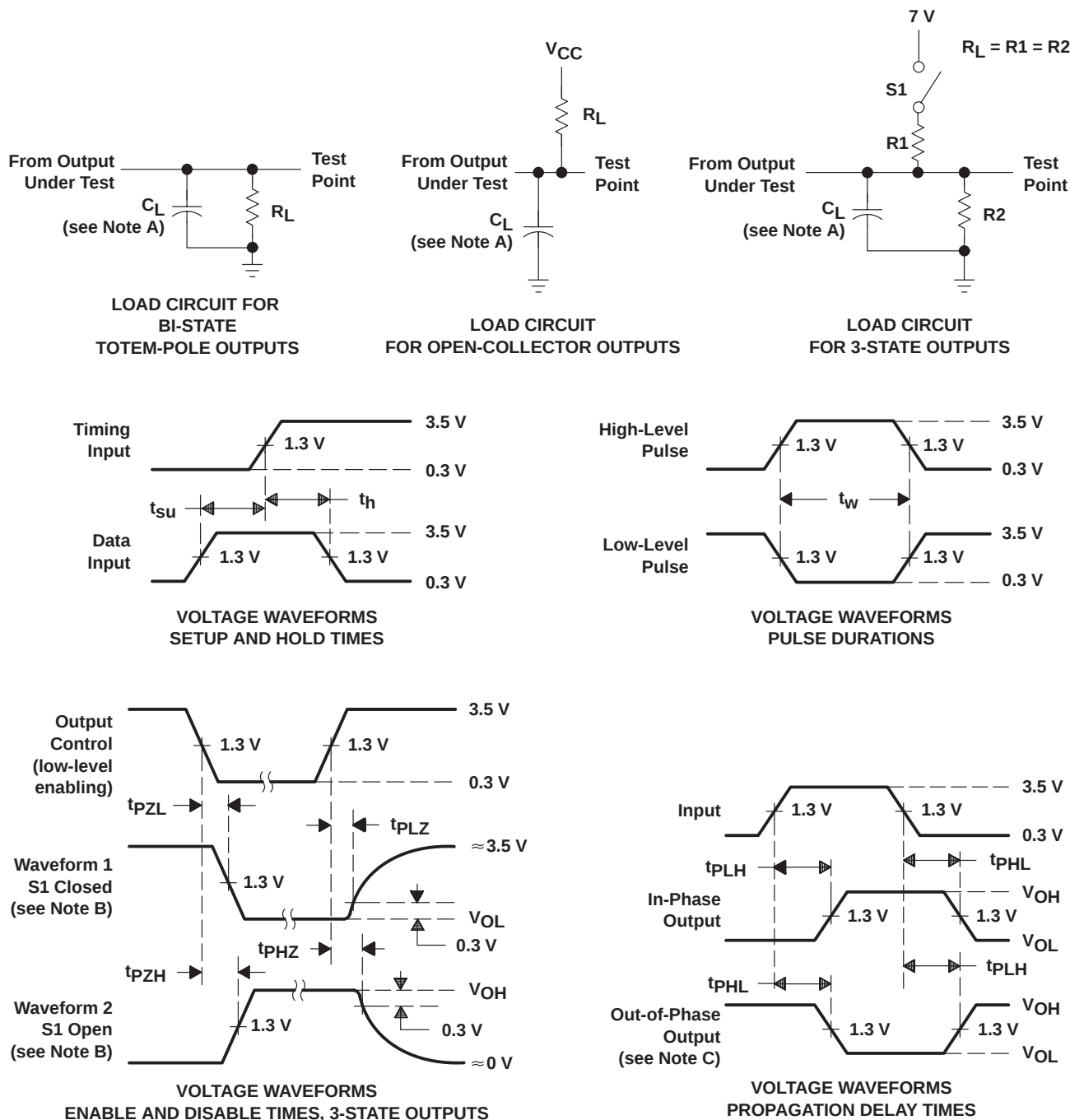
[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX [¶]		UNIT
			MIN	MAX	
t _{PLH}	A or B	Y	1	6	ns
t _{PHL}			1	6	

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AS1008AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS1008ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS1008ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS1008ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS1008AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AS1008ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

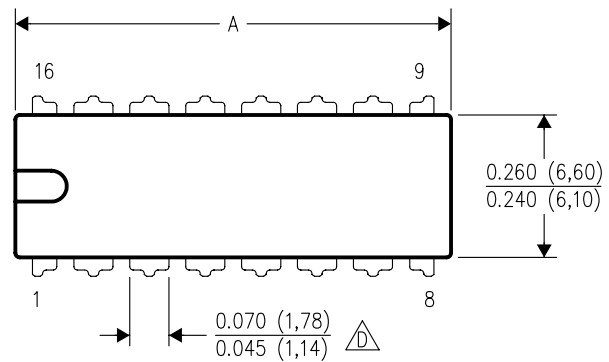
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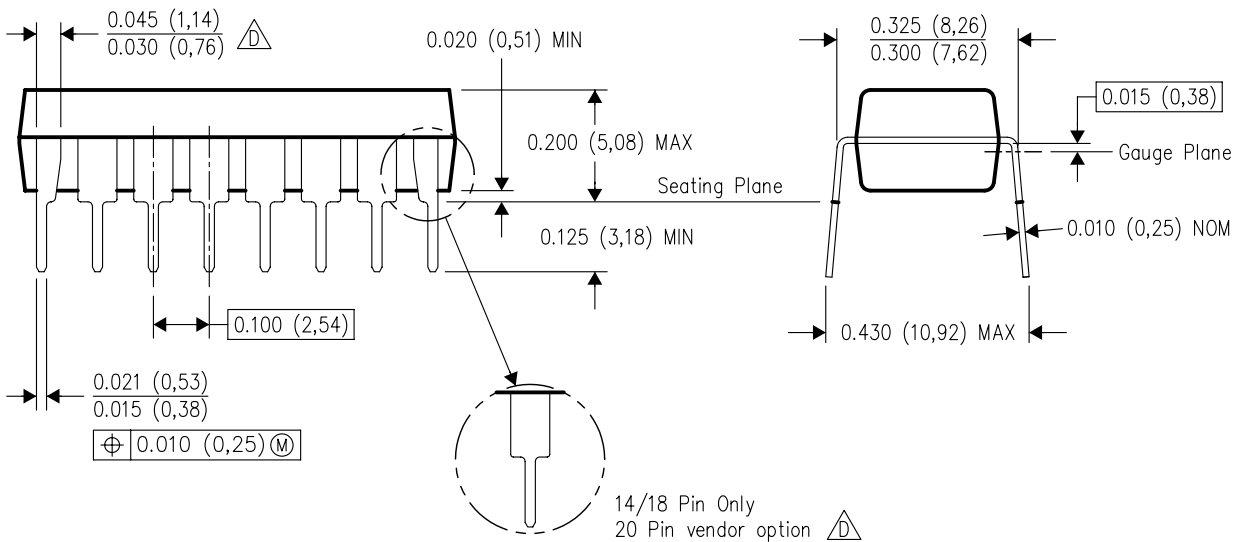
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



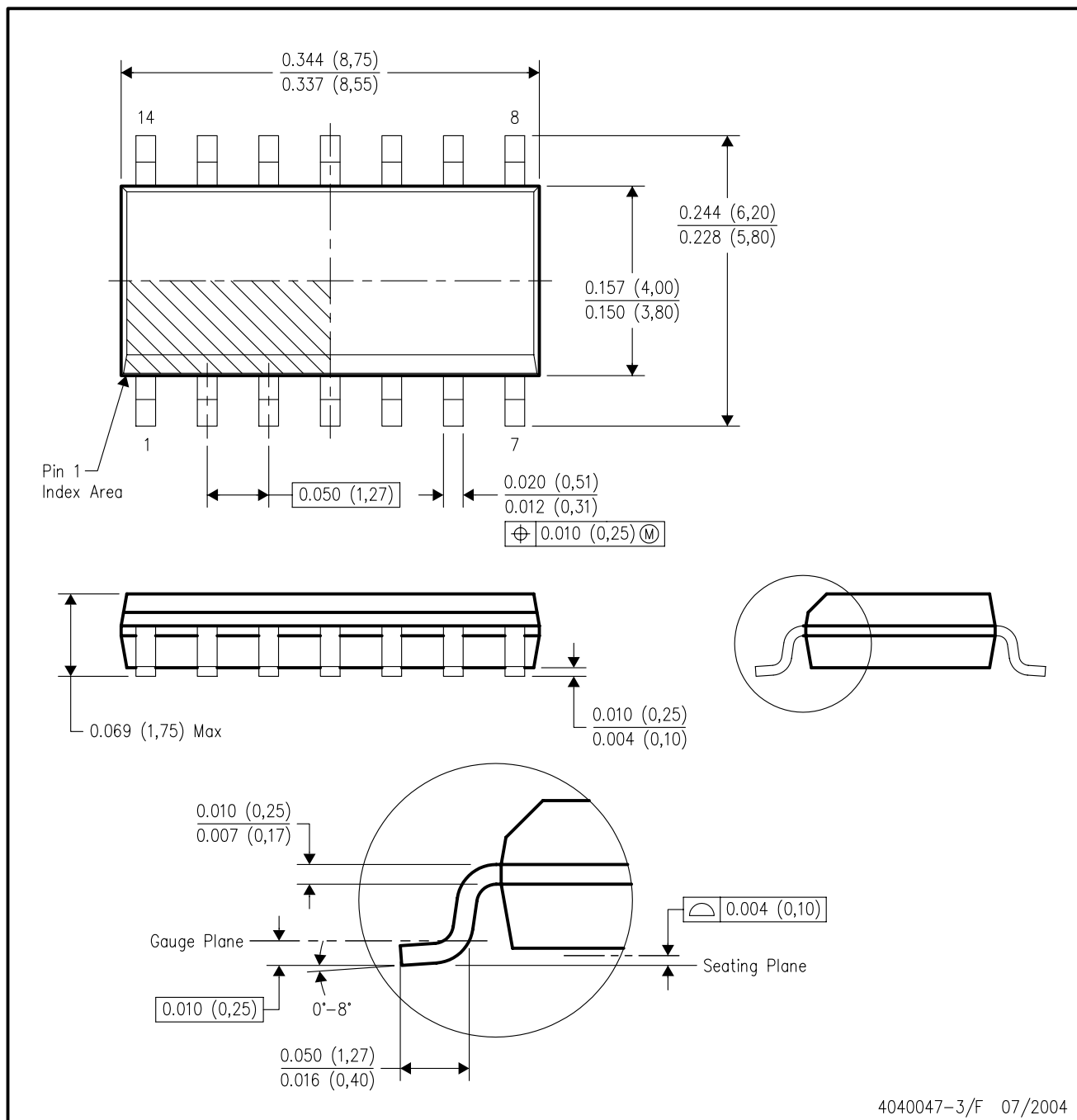
14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

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